

PWM Control 3A Step-Down Converter

❖ GENERAL DESCRIPTION

AX3103 consists of step-down switching regulator with PWM control. These devise include a reference voltage source, oscillation circuit, error amplifier, internal PMOS and etc.

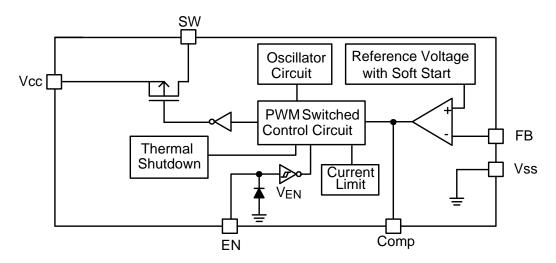
AX3103 provides low-ripple power, high efficiency, and excellent transient characteristics. The PWM control circuit is able to the duty ratio linearly form 0 up to 100%. This converter also contains an error amplifier circuit as well as a soft-start circuit that prevents overshoot at startup. An enable function, an over current protect function and short circuit protect function are built inside, and when OCP or SCP happens, the operation frequency will be reduced. Also, an internal compensation block is built in to minimum external component count.

With the addition of an internal P-channel Power MOS, a coil, capacitors, and a diode connected externally, these ICs can function as step-down switching regulators. They serve as ideal power supply units for portable devices when coupled with the SOP-8L package, providing such outstanding features as low current consumption. Since this converter can accommodate an input voltage up to 23V, it is also suitable for the operation via an AC adapter.

FEATURES

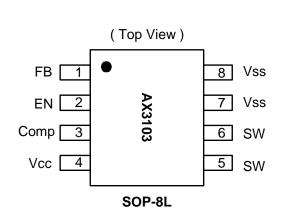
- Input voltage : 3.6V to 23VOutput voltage : 0.8V to V_{CC}
- Duty ratio: 0% to 100% PWM control
- Oscillation frequency: 330KHz typ.
- Soft-start (SS), Current Limit (CL), Enable function.
- Thermal Shutdown function.
- Short Circuit Protect (SCP).
- Built-in internal SW P-channel MOS.
- Low ESR output capacitor (Multi-layer chip capacitor (MLCC)) application.
- SOP-8L Pb-Free package.

❖ BLOCK DIAGRAM



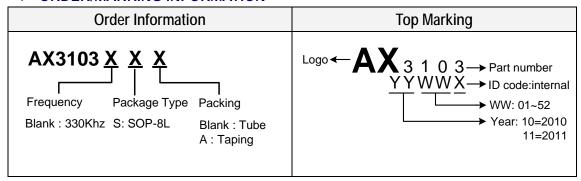
❖ PIN ASSIGNMET

The package of AX3103 is SOP-8L; the pin assignment is given by:



Name	Description				
FB	Feedback pin				
EN	Power-off pin H: normal operation(Step-down) L: Step-down operation stopped (All circuits deactivated)				
Comp	Compensation pin				
Vcc	IC power supply pin				
SW	Switch pin. Connect external inductor/diode here.				
V _{SS}	GND pin				

ORDER/MARKING INFORMATION



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❖ ABSOLUTE MAXIMUM RATINGS (at T_A=25°C)

Characteristics	Symbol	Rating	Unit
VCC Pin Voltage	Vcc	V _{SS} - 0.3 to V _{SS} + 25	V
Feedback Pin Voltage	V_{FB}	V_{SS} - 0.3 to V_{CC}	V
ON/OFF Pin Voltage	V _{EN}	V_{SS} - 0.3 to V_{CC} + 0.3	V
Switch Pin Voltage	V _{SW}	V_{SS} - 0.3 to V_{CC} + 0.3	V
Power Dissipation	PD	Internally limited	mW
Storage Temperature Range	T _{ST}	-40 to +150	°C
Operating Junction Temperature Range	TJ	-20 to +125	°C
Operating Supply Voltage	V _{OP}	+3.6 to +23	V
Thermal Resistance from Junction to case	θ_{JC}	25	°C/W
Thermal Resistance from Junction to ambient	θја	70	°C/W

Note: θ JA is measured with the PCB copper area (need connect to SW pins) of approximately 1 in² (Multi-layer).

❖ ELECTRICAL CHARACTERISTICS

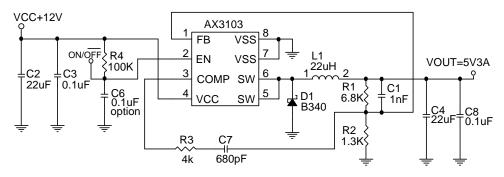
(V_{IN} = 12V, T_A=25°C, unless otherwise specified)

Characteristics	Symbol	Condi	itions	Min	Тур	Max	Units
Feedback Voltage	V_{FB}	I _{OUT} =0.2A		0.784	8.0	0.816	V
Quiescent Current	I _{CCQ}	V_{FB} =1.2V for off	orce driver		3	5	mA
Feedback Bias Current	I_{FB}	I _{OUT} =0.2A			0.1	0.5	uA
Shutdown Supply Current	I_{SD}	V _{EN} =0V		-	2	10	uA
Current Limit	I _{CL}			4.0	-	-	Α
Line Regulation	△Vоит/Vоит	V _{CC} = 5V~23 I _{OUT} =0.2A	V,	-	0.6	1.2	%
Load Regulation	\triangle V _{OUT} /V _{OUT}	$I_{OUT} = 0.2$ to	3A	-	0.2	0.4	%
Oscillation Frequency	Fosc	SW pin		260	330	400	KHz
EN Pin Logic input	V_{SH}	High (regulator ON)		2.0	1	ı	V
threshold voltage	V_{SL}	Low (regulat	or OFF)		1	8.0	V
EN Pin Input Current	I _{SH}	V _{EN} =2.5V (ON)		-	20	ı	uA
EN FIII IIIput Guireiit	I_{SL}	V _{EN} =0.3V (OFF)		-	-10	-	uA
Soft-Start Time	T_{SS}			-	20	-	ms
Internal MOSEET Day	D	V _{CC} =5V, V _{FB} =0V		-	90	140	m0
Internal MOSFET R _{DSON}	R_{DSON}	V _{CC} =12V, V _{FB} =0V		-	60	90	mΩ
Efficiency	EFFI	\/ - 5\/	I _{OUT} = 2A	-	92	-	%
Efficiency		$V_{OUT} = 5V$	I _{OUT} = 3A	-	91	-	70
Thermal shutdown Temp	T _{SD}				125		°C



❖ APPLICATION CIRCUIT

MLCC

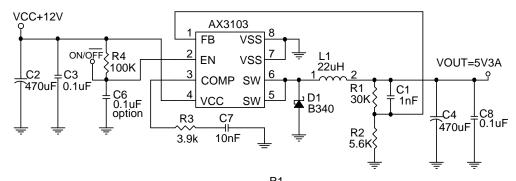


VOUT= VFB x
$$(1 + \frac{R1}{R2})$$

VFB= $0.8\,V$; R2 suggest $0.8K \sim 3.0K$

Compensation Capacitor Selection(MLCC)							
VIN	VIN V _{OUT} L1 R3 C7 C1						
12V	5.0/3.3/2.5V	15uH	4K	680pF	1nF		
5V 3.3/2.5V 15uH 6.8K 330pF 1n							

EL CAP



VOUT= VFB x $(1 + \frac{R1}{R2})$

VFB=0.8V; R2 suggest 0.8K ~ 6.0K

Compensation Capacitor Selection(EL CAP)						
VIN V _{OUT} L1 R3 C7 C1						
5-20V 5/3.3/2.5/1.8V 15uH 3.9K 10nF 1nF						



FUNCTION DESCRIPTIONS

PWM Control

The AX3103 consists of DC/DC converters that employ a pulse-width modulation (PWM) system. In converters of the AX3103, the pulse width varies in a range from 0 to 100%, according to the load current. The ripple voltage produced by the switching can easily be removed through a filter because the switching frequency remains constant. Therefore, these converters provide a low-ripple power over broad ranges of input voltage and load current.

Setting the Output Voltage

Application circuit item shows the basic application circuit with adjustable output version. The external resistor sets the output voltage according to the following equation:

$$V_{OUT} = 0.8V \times \left(1 + \frac{R1}{R2}\right)$$

Table 1 Resistor select for output voltage setting

V_{OUT}	Cout	R2	R1
5V	EL	1.3K	6.8K
37	MLCC	7.5K	39K
3.3V	EL	1.5K	4.7K
3.37	MLCC	15K	47K
2.5V	EL	2.2K	4.7K
	MLCC	22K	47K
1.8V	EL	2K	2.5K
1.5V	EL	2.2K	2.0K
1.2V	EL	3K	1.5K

Inductor Selection

For most designs, the operates with inductors of 12µH to 33µH. The inductor value can be derived from the following equation:

$$L = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} \times \Delta I_{L} \times f_{OSC}}$$

Where is inductor Ripple Current. Large value inductors lower ripple current and small value inductors result in high ripple currents. Choose inductor ripple current approximately 20% of the maximum load current 3A, ΔI_L =0.4A. The DC current rating of the inductor should be at least equal to the maximum load current plus half the ripple current to prevent core saturation (3A+0.2A).

Input Capacitor Selection (EL CAP)

This capacitor should be located close to the IC using short leads and the voltage rating should be approximately 1.5 times the maximum input voltage. The RMS current rating requirement for the input capacitor of a buck regulator is approximately 1/2 the DC load current. A low ESR input capacitor sized for maximum RMS current must be used. A 220µF low ESR capacitor for most applications is sufficient.

(MLCC CAP)

A 22µF MLCC or greater capacitor for most applications is sufficient.

Output Capacitor Selection

(EL CAP)

The output capacitor is required to filter the output and provide regulator loop stability. The important capacitor parameters are; the 100KHz Equivalent Series Resistance (ESR), the RMS ripples current rating, voltage rating, and capacitance value. For the output capacitor, the ESR value is the most important parameter. The ESR can be calculated from the following formula.

$$V_{RIPPLE} = \Delta I_L \times ESR = 0.4$$
A x 110m Ω = 44mV

An aluminum electrolytic capacitor's ESR value is related to the capacitance and its voltage rating. In most case, higher voltage electrolytic capacitors have lower ESR values. Most of the time, capacitors with much higher voltage ratings may be needed to provide the low ESR values required for low output ripple voltage. It is recommended to replace this low ESR capacitor by using a $330\mu\text{F}$ low ESR values < $110m\,\Omega$.

(MLCC CAP)

A 22µF MLCC capacitor for most applications is sufficient.

Note: MLCC do not support when V_{OUT} is smaller than 2.5V.

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RDS (ON) Current Limiting

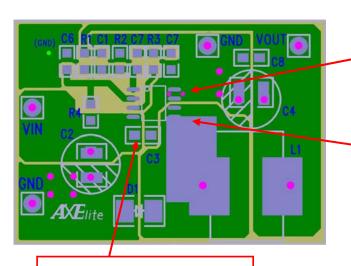
The current limit threshold is setting by the internal circuit.

V _{IN}	4V~4.7V	4.7V~20V	
I _{CL} (MIN)	3.3A	4A	
I _{OUT} (MAX)	2.5A	3A	

PCB Layout Guide

If you need low Tc and Tj or large PD (Power Dissipation), the dual SW pins (5 and 6) and V_{SS} pins (7 and 8) on the SOP-8L package are internally connected to die pad, The PCB layout should allow for maximum possible copper area at the SW pins.

- 1. Connect C3 to V_{CC} and V_{SS} pin as closely as possible to get good power filter effect.
- 2. Connect ground side of the C2 and D1 as closely as possible.



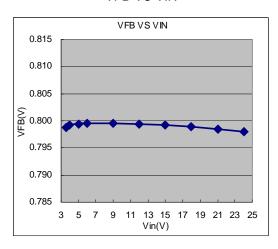
Use through hole to conduct the heat into the backside of PCB

The heat sink copper of PCB area should be solder-painted without masked.

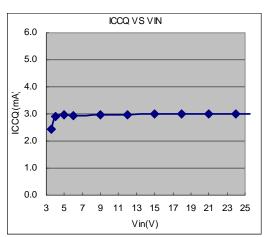
Bypass C3 need closely from IC's V_{CC} to V_{SS} pins.

TYPICAL CHARACTERISTICS

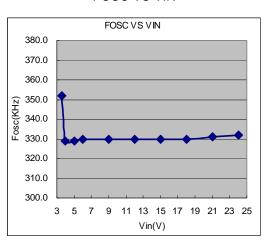
VFB VS VIN



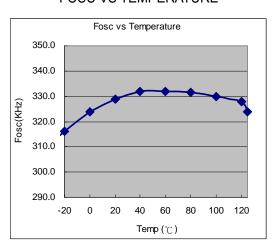
ICCQ VS VIN



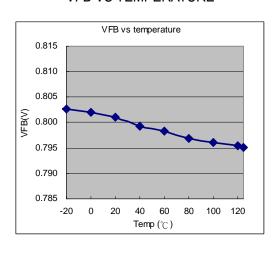
FOSC VS VIN



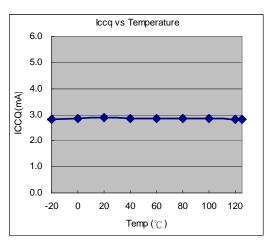
FOSC VS TEMPERATURE



VFB VS TEMPERATURE

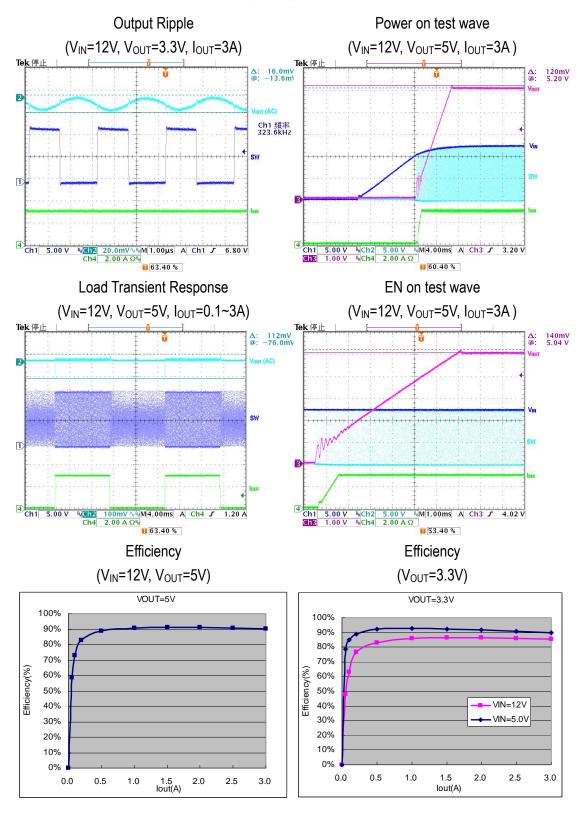


ICCQ VS TEMPERATURE

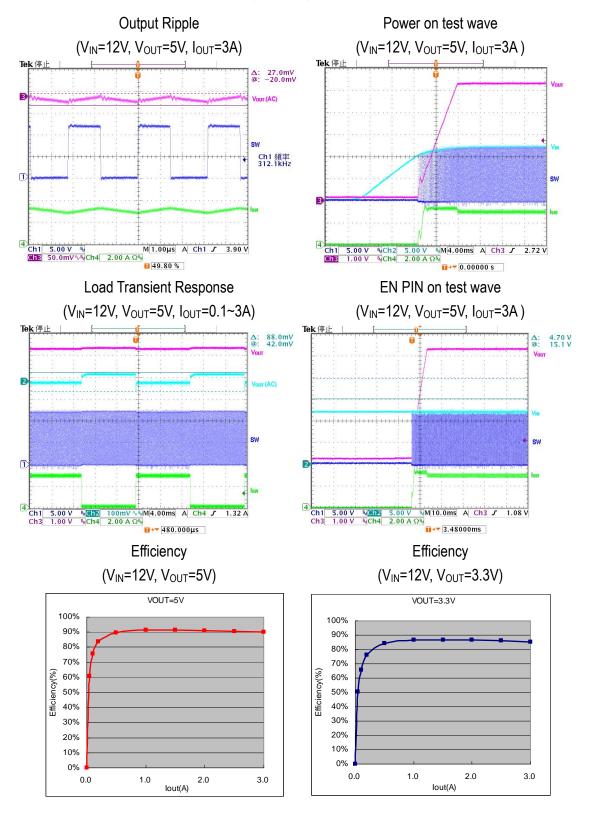




TYPICAL CHARACTERISTICS (MLCC)

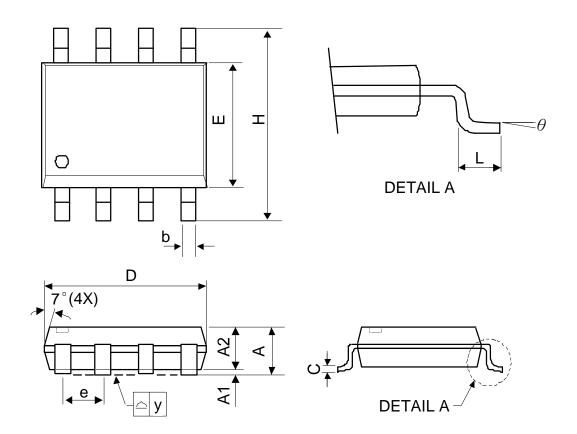


TYPICAL CHARACTERISTICS (AL CAP)





❖ PACKAGE OUTLINES



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
А	-	-	1.75	-	-	0.069
A1	0.1	-	0.25	0.04	-	0.1
A2	1.25	-	-	0.049	-	-
С	0.1	0.2	0.25	0.0075	0.008	0.01
D	4.7	4.9	5.1	0.185	0.193	0.2
Е	3.7	3.9	4.1	0.146	0.154	0.161
Н	5.8	6	6.2	0.228	0.236	0.244
L	0.4	-	1.27	0.015	-	0.05
b	0.31	0.41	0.51	0.012	0.016	0.02
е	1.27 BSC			().050 BSC	
у	-	-	0.1	-	-	0.004
θ	00	-	8°	00	-	8 0

Mold flash shall not exceed 0.25mm per side

JEDEC outline: MS-012 AA